

Specification
For
LTCC 3dB Hybrid Coupler

Model Name : RCP2250C03

<p><i>Customer :</i></p> <p><i>Title:</i> _____</p> <p><i>Name :</i></p> <p><i>APPROVED</i></p> <p style="text-align: right;"><i>By Date :</i> _____</p> <p style="text-align: right;"><i>Signature :</i> _____</p>
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RN2 Technologies co., Ltd.

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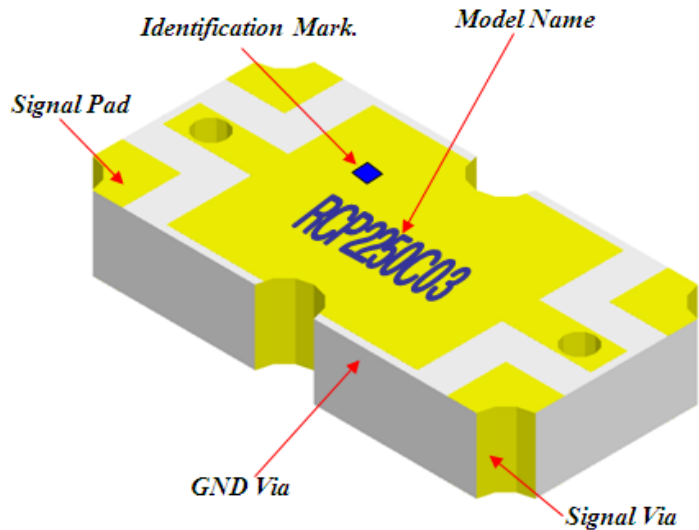
Issued Date : _____

Designed : _____

Approved : _____

1. Description

1-1. Part number: RCP2250C03



1-2. Features

- Hybrid Coupler 3dB, 90°
- Surface mount type
- Suitable for operation frequency 2100~2400MHz
- **RoHS** compliance
- High stability in temperature and humidity for LTCC base
- Low loss for Silver(Ag) conductor
- Miniature size and high power capability
- Lead-free alloy solderable
- Thermal expansion corresponding with common substrate

2. Electrical Specification

Freq. (MHz)	Amplitude Balance max (dB)	Isolation min (dB)	Insertion Loss max (dB)
2100-2400	± 0.25	-20	-0.5
VSWR Max	Phase (degrees)	Power Capacity Avg. (Watt)	Operating Temp. (°C)
1.2	90 ± 3.0	20	-55 to +125

3. Mechanical Specification

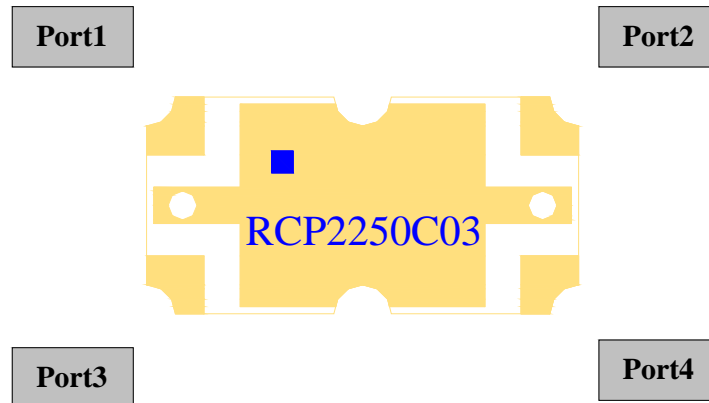
3-1. Outline Dimension

PROJECTION	NO.	DATE	REVISION & DESCRIPTION	SIGNATURE		
				REVIEWED	CHECKED	
	1	2009.04.20	New-Drawing			
	2					
	3					
<p>Note.</p> <ol style="list-style-type: none"> 1. SMD-type, Ceramic Base. 2. Inner signal circuits : Silver(Ag) conductor 3. Surface plating : Gold(Au) finished 4. Tolerance is not cumulative. 						
NO.	DESCRIPTION		UNIT	TOTAL		
			QUANTITY			
TITLE	C size-Outline	RN2 DWG NO.	09-0420-01	SCALE	1/1	
				SIZE	A4	DIMENSION mm

3-2. Weight

- 0.15 Grams typical

4. Port Configuration



Configuration	Port 1	Port 2	Port 3	Port 4
Case 1.	Input	Isolated	Coupling -3dB, 0°	Output -3dB, -90°
Case 2.	Isolated	Input	Output -3dB, 90°	Coupling -3dB, 0°
Case 3.	Coupling -3dB, 0°	Output -3dB, 90°	Input	Isolated
Case 4.	Output -3dB, 90°	Coupling -3dB, 0°	Isolated	Input

* Once Port 1 is determined, the other three ports are defined automatically.

5. Schematic Drawing

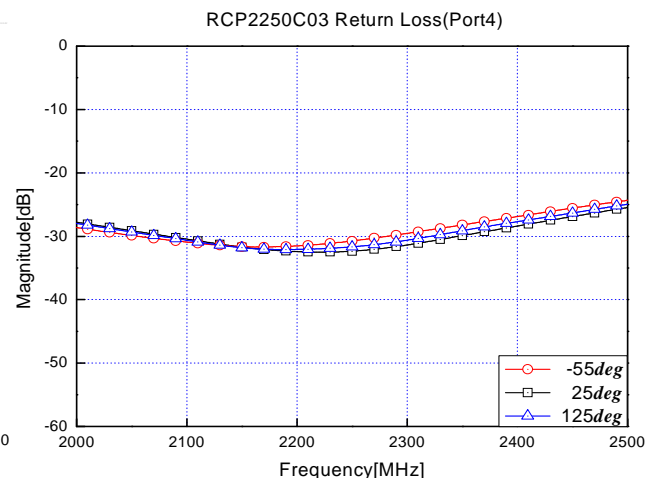
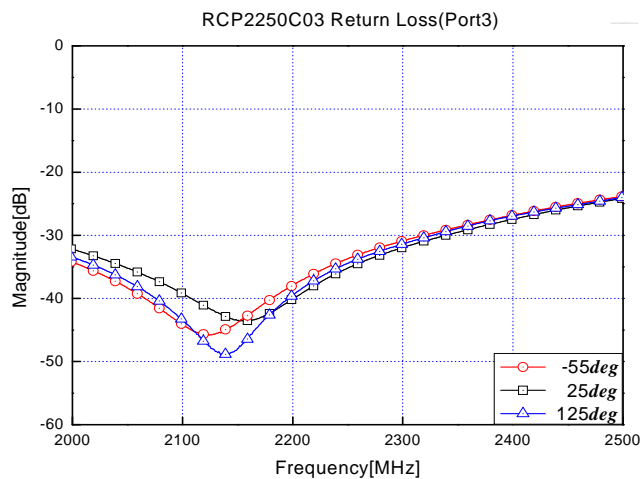
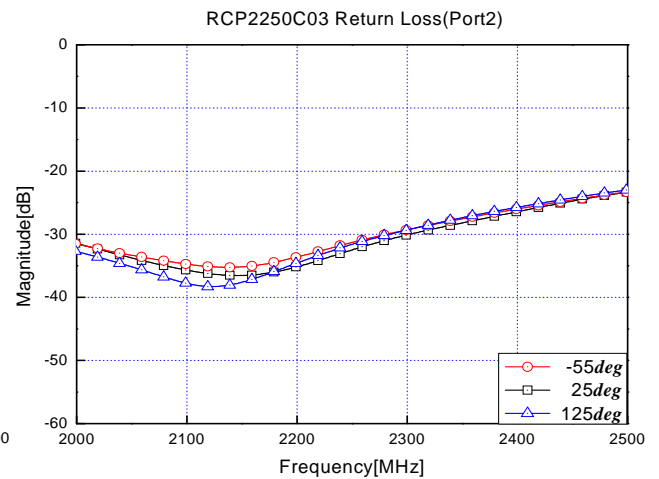
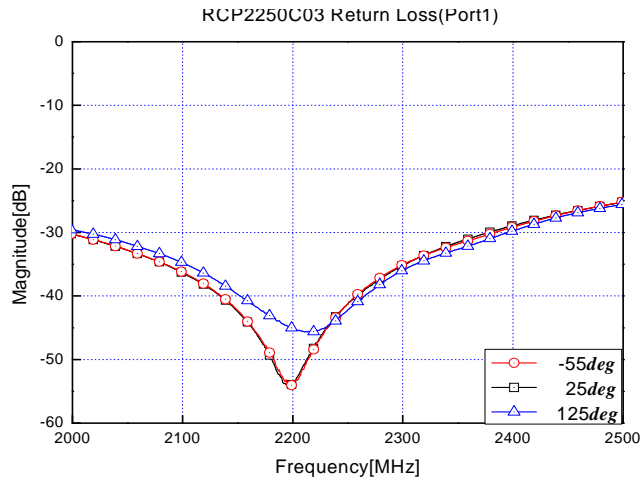


6. Typical Performance Data (25 °C)

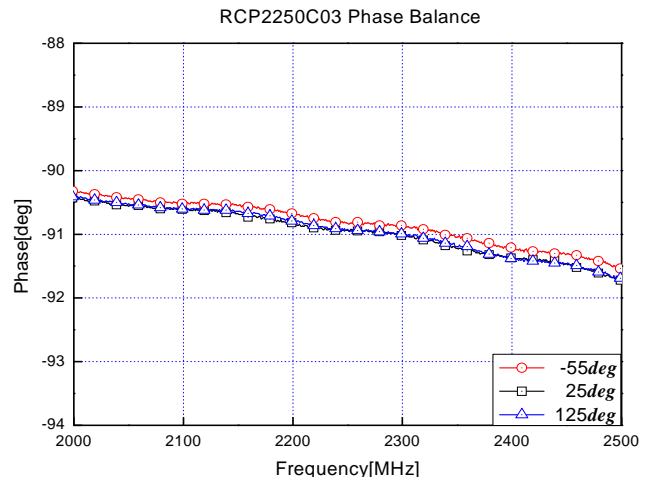
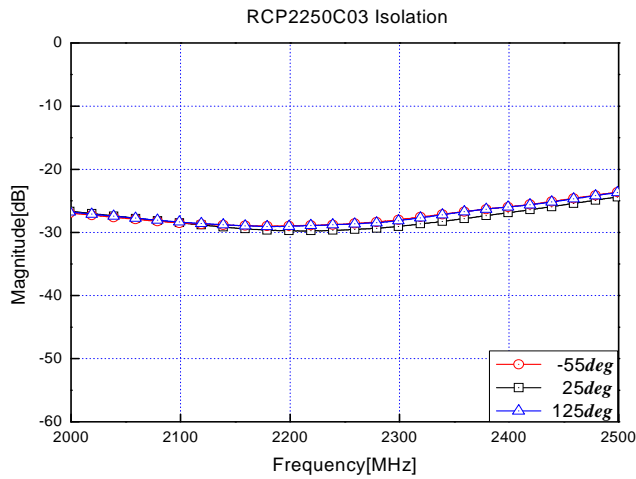
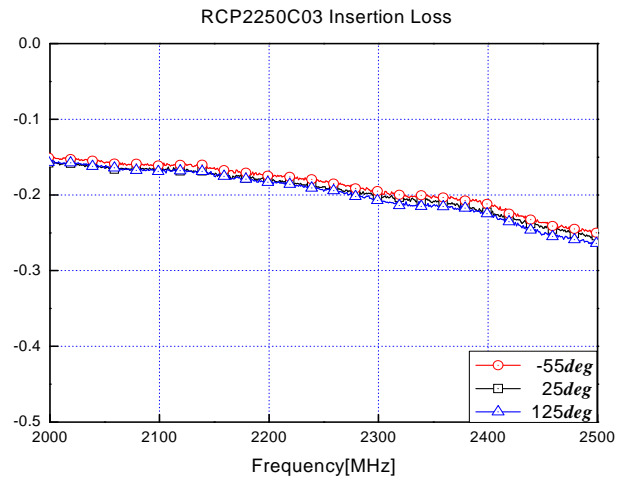
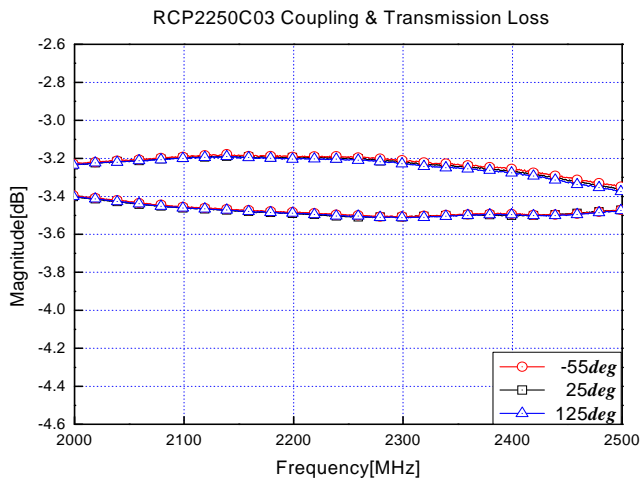
Freq. [MHz]	Coupling [dB]	Out [dB]	IL [dB]	Amp.Bal. [dB]	Isolation [dB]	Phase [degree]	Return Loss [dB]			
							S11	S22	S33	S44
2100	-3.20	-3.46	-0.17	±0.13	-28.50	-90.61	-36.36	-35.7	-39.22	-30.44
2120	-3.19	-3.47	-0.17	±0.14	-28.83	-90.62	-38.3	-36.25	-41.16	-30.97
2140	-3.19	-3.47	-0.17	±0.14	-29.17	-90.66	-40.83	-36.52	-42.98	-31.47
2161	-3.19	-3.48	-0.17	±0.15	-29.45	-90.71	-44.56	-36.42	-43.45	-31.92
2180	-3.19	-3.48	-0.18	±0.14	-29.66	-90.77	-49.48	-35.97	-42.30	-32.23
2200	-3.20	-3.49	-0.18	±0.15	-29.73	-90.84	-53.77	-35.18	-40.12	-32.42
2220	-3.20	-3.50	-0.18	±0.15	-29.75	-90.89	-47.87	-34.11	-37.93	-32.51
2240	-3.20	-3.50	-0.19	±0.15	-29.68	-90.94	-43.1	-33.04	-36.01	-32.44
2250	-3.20	-3.51	-0.19	±0.15	-29.60	-90.94	-41.24	-32.51	-35.23	-32.36
2260	-3.20	-3.51	-0.19	±0.15	-29.52	-90.94	-39.83	-31.96	-34.46	-32.22
2280	-3.21	-3.51	-0.20	±0.15	-29.35	-90.96	-37.23	-30.95	-33.10	-31.85
2300	-3.22	-3.51	-0.20	±0.14	-29.02	-91.01	-35.2	-30.11	-31.94	-31.37
2320	-3.23	-3.50	-0.20	±0.14	-28.66	-91.09	-33.54	-29.29	-30.91	-30.8
2340	-3.24	-3.50	-0.21	±0.13	-28.24	-91.15	-32.14	-28.57	-29.98	-30.19
2360	-3.25	-3.50	-0.21	±0.13	-27.78	-91.27	-30.98	-27.85	-29.11	-29.58
2380	-3.25	-3.50	-0.21	±0.12	-27.32	-91.33	-29.88	-27.12	-28.26	-28.99
2400	-3.27	-3.50	-0.22	±0.12	-26.88	-91.35	-28.92	-26.44	-27.47	-28.38

* IL data is excluding PCB and Connector Loss (2.25 GHz = 0.15dB)

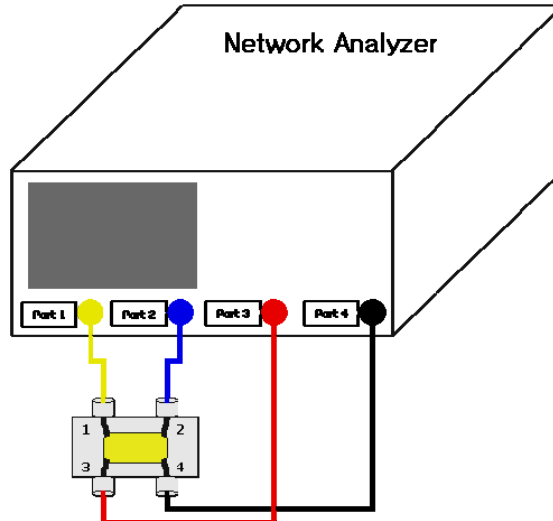
7. Operation Temperature Curve (a)



8. Operation Temperature Curve (b)



9. Test Method



- Refer to 'Case 1' of '4. Port Configuration' on page 4
- Have the network analyzer calibrated properly.
- Measure the data of **Coupling** through port 1 to port 3. (S31)
- Measure the data of **Transmission** through port 1 to port 4. (S41)
- Measure the data of **Isolation** through port 1 to port 2. (S21)
- Calculate the **Insertion Loss** and **Amplitude Balance** of coupler on the below power method formula.

	S-Parameter[dB]	Power Method[dB]
Coupling	S31	$10 \cdot \log\left(\frac{P_{cou}}{P_{in}}\right)$
Transmission Loss	S41	$10 \cdot \log\left(\frac{P_{out}}{P_{in}}\right)$
Isolation	S21	$10 \cdot \log\left(\frac{P_{iso}}{P_{in}}\right)$
Insertion Loss		$10 \cdot \log\left(\frac{P_{in}}{P_{cou} + P_{out}}\right)$
Amplitude Balance		$10 \cdot \log\left(\frac{P_{cou}}{\frac{P_{cou} + P_{out}}{2}}\right)$
Phase Balance	$\text{Phase}_{(S31)} - \text{Phase}_{(S41)}$	

P_{in} : Power of Input Port

P_{out} : Power of Output Port

P_{cou} : Power of Coupling Port

P_{iso} : Power of Isolated Port

10. Measurement board layout

PROJECTION	No.	DATE	REVISION & DESCRIPTION	SIGNATURE	
				REVIEWED	CHECKED
	1	2008.11.14	New - Drawing		
	2				
	3				

NOTE. Signal line width is shown for the conditions of;

- FR-4 board
- Dielectric contance 4.4
- Board thickness 0.4mm
- Copper thickness 1/2 oz.

No.	DESCRIPTION	UNIT	TOTAL	PERUNIT	TOTAL				
		QUANTITY				SCALE			
TITLE	C size Coupler-Measuremnet Board Outline	RN2 DWG No.	08-1114-02		SCALE	1/1			
					SIZE	A4	DIMENSION	mm	

11. Recommended PCB layout and Solder mask pattern

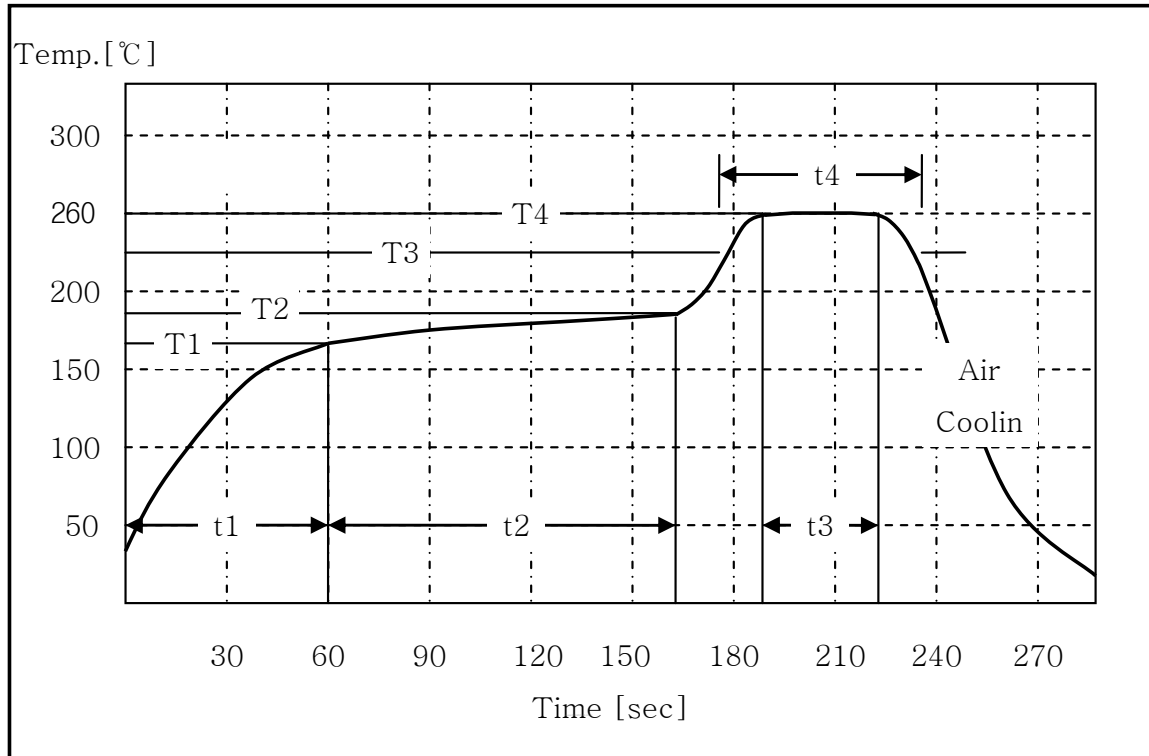
PROJECTION	No.	DATE	REVISION & DESCRIPTION	SIGNATURE	
				REVIEWED	CHECKED
	1	2008.11.12	New - Drawing		
	2				
	3				

NOTE.

1. Test Solder Cream : SAC-305 (Alpa Metal)
2. Lead Free Solder Alloy : Sn/Ag/Cu Ratio Of 96.5/3.0/0.5
3. Solder Area ('A') Demension : 0.88 mm by 0.74 mm
4. Solder Area ('B') Demension : 1.74 mm by 0.4 mm

No.	DESCRIPTION	UNIT	TOTAL	PERUNIT	TOTAL	SCALE	1/1	DIMENSION	mm
			QUANTITY						
TITLE	C size - Recommended Solder Quantity &Area	RN2 DWG No.	08-1112-01			SIZE	A4		

12. Reflow profile



	Ramp Up	Pre-Heating	Peak	Soaking
Temp.[°C]	T1:160±5°C	T2:180±5°C	T4:260±5°C	T3:230±5°C
Time [sec]	t1:60±5sec	t2:100±15sec	t3:30±5sec	t4:60±10sec



13. Using note for LTCC Couplers

I. Be careful when transporting

- A. Excessive stress or shock may make products broken or cracked due to the nature of ceramics structure.
- B. The products cracked or damaged on terminals may have their property changed.

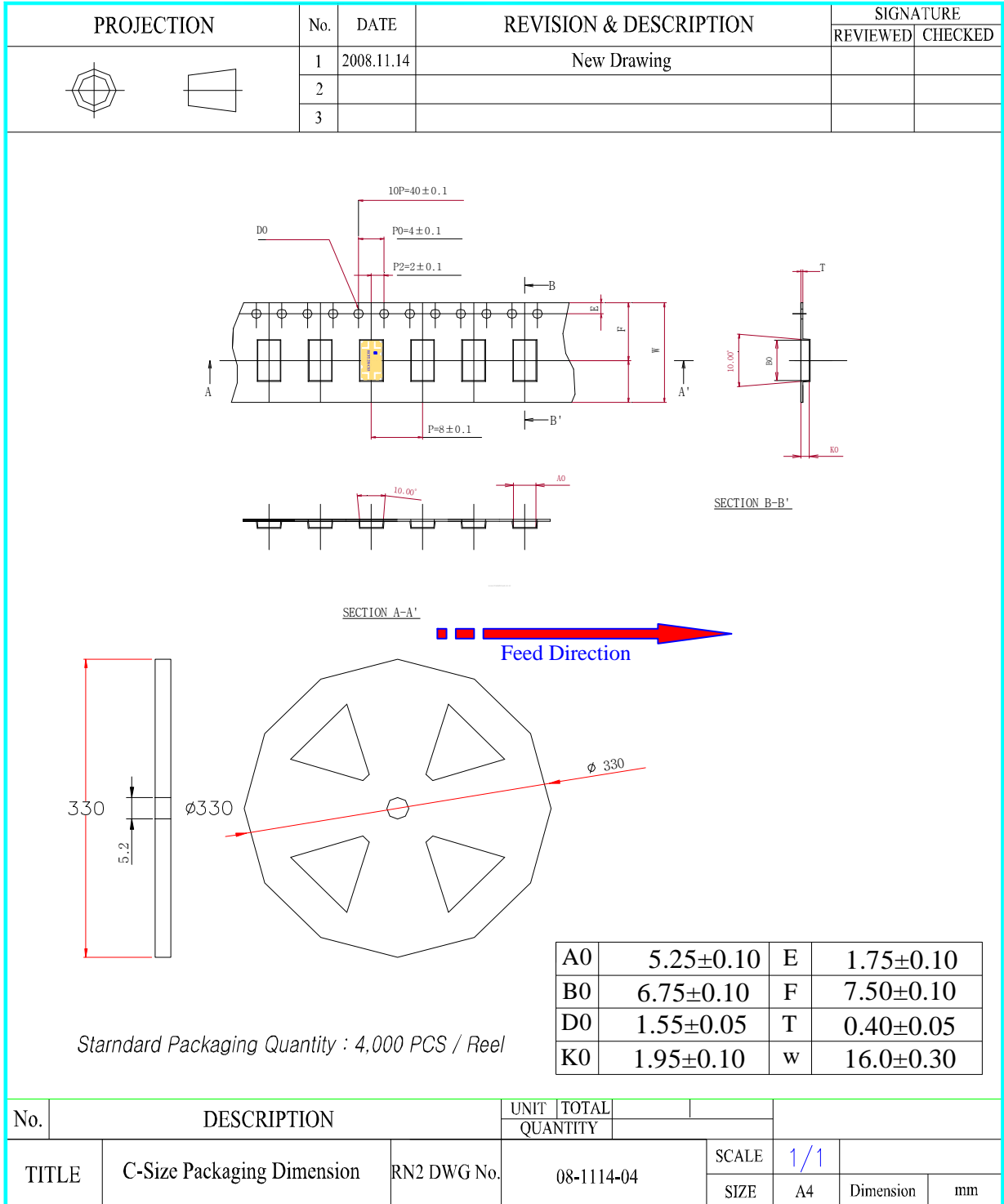
II. Be careful during storage

- A. Store the products in the temperature of $-55 \sim 125^{\circ}\text{C}$
- B. Keep the humidity at $45 \sim 75\%$ around the products.
- C. Prevent corrosive gas (Cl_2 , NH_3 , SO_x , NO_x , etc.) from contacting the products.
- D. It is recommended to use the products within 6 months of receipt. If the period exceeds 6 months, solderability may need to be verified.

III. Be careful when soldering

- A. All the ground terminals, IN and OUT pad of coupler should be soldered on the ground plane of the PCB.
- B. Products may be cracked or broken by uneven forces from a claw or suction device.
- C. Mechanical stress by any other devices may damage products when positioning them on PCB.
- D. A dropped product is recommended not to be used.
- E. Soldering must be carried out by the condition of specification sheet.
- F. Any couplers which are de-soldered from PCB should not be used again.

14. Packaging



15. Environmental Reliability

ITEM	PROCEDURE	REQUIREMENTS/RESULT
Temperature Cycle (Thermal Shock)	1. One Cycle : 30 min Step1: 125 ± 5 °C for 15 min Step2: -55 ± 5 °C for 15 min 2. Approach high or low temperature in 10 seconds 3. Number of Cycles : 100 4. Normal temperature for 1 hour	1. Meet the electrical Specification after test
Solderability	1. Solder : 230 ± 5°C for 5± 1 sec.	1. More than 85% of the I/O electrode pad shall be covered with solder.
Heat Resistance	1. Temperature : 100 ± 2 °C 2. Duration : 96 ± 2 hours	1. Meet the electrical Specification after test
Low Temp. Resistance	1. Temperature : -55 ± 5 °C 2. Duration : 24 ± 2 hours	1. Meet the electrical Specification after test
Vibration Resistance	1. Frequency: 5~ 15MHz 2. Acceleration : 10g 3. Sweep Time: 0.1 oct/min, 15min/axis 4. Axis : X, Y and Z direction	1. No appearance damage 2. Meet the electrical Specification after test
Humidity Resistance	1. One Cycle : Step1: increase Temperature -25~65°C for 2hours with humidity 85% Step2: Maintain for 4 hour after increasing Humidity 90% to 95% Step3: Decrease Temperature 65°C to 25°C 2. Number of Cycles : 10 3. Maintain for 3hour after decreasing temperature -10°C	1. Meet the electrical Specification after test
Drop Shock	1. Dropped onto hard wood from height of 50 cm for 5 times; each x, y and z direction except I/O direction.	1. No appearance damage 2. Meet the electrical Specification after test

16. RoHS test result

- RN2 Technologies warrants and represents as follows.

Test Report No. F690501/LF-CTSGP06-16067

Date: June 29, 2008

Page 2 of 3

Sample No. : GP06-16067.001
Sample Description : LTCC COUPLER
Style/Item No. : N/A
Comments : Materials are ceramics, Ag.

Heavy Metals

Test items	Unit	Test Method	MDL	Results
Cadmium(Cd)	mg/kg	US EPA 3050B(1996), US EPA 6010B(1996), ICP	0.5	N.D.
Lead (Pb)	mg/kg	US EPA 3050B(1996), US EPA 6010B(1996), ICP	5	N.D.
Mercury (Hg)	mg/kg	US EPA 3052(1996), US EPA 6010B(1996), ICP	2	N.D.
Hexavalent Chromium (Cr VI)	mg/kg	US EPA 3060A(1996), US EPA 7196A(1992), UV	1	N.D.

Flame Retardants-PBBs/PBDEs

Test items	Unit	Test Method	MDL	Results
Monobromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Dibromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tribromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tetrabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Pentabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Hexabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Heptabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Octabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Nonabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Decabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Monobromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Dibromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tribromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tetrabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Pentabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Hexabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Heptabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Octabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Nonabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Decabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.

NOTE: (1) N.D. = Not detected.(<MDL)
 (2) ppm = mg/kg
 (3) MDL = Method Detection Limit
 (4) - = No regulation
 (5) ** = Qualitative analysis (No Unit)
 (6) Negative = Undetectable / Positive = Detectable

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